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SERIAL NUMBER 10/687,085	FILING DATE 10/17/2003 RULE	CLASS 438	GROUP ART UNIT 2813	ATTORNEY DOCKET NO. 244081US2	
APPLICANTS Hiroshi Maeda, Tokyo, JAPAN; ** CONTINUING DATA ***** None S.W.S. ** FOREIGN APPLICATIONS ***** S.W.S. JAPAN 2003-144390 05/22/2003 IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 01/16/2004					
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met <i>S.W.S.</i> Verified and Acknowledged <i>S.W.S.</i> Examiner's Signature Initials		STATE OR COUNTRY JAPAN	SHEETS DRAWING 12	TOTAL CLAIMS 5	INDEPENDENT CLAIMS 1
ADDRESS 22850 OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C. 1940 DUKE STREET ALEXANDRIA, VA 22314					
4-18-05 TITLE <i>Flip Chip Mounting Method of Forming a Solder Bump on a Chip Pad that is Exposed Through an Opening Formed in a Polyimide Film that Flip chip mounting method Includes Utilizing Underfill to Bond the Chip to a Substrate</i>					
FILING FEE RECEIVED 770	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		